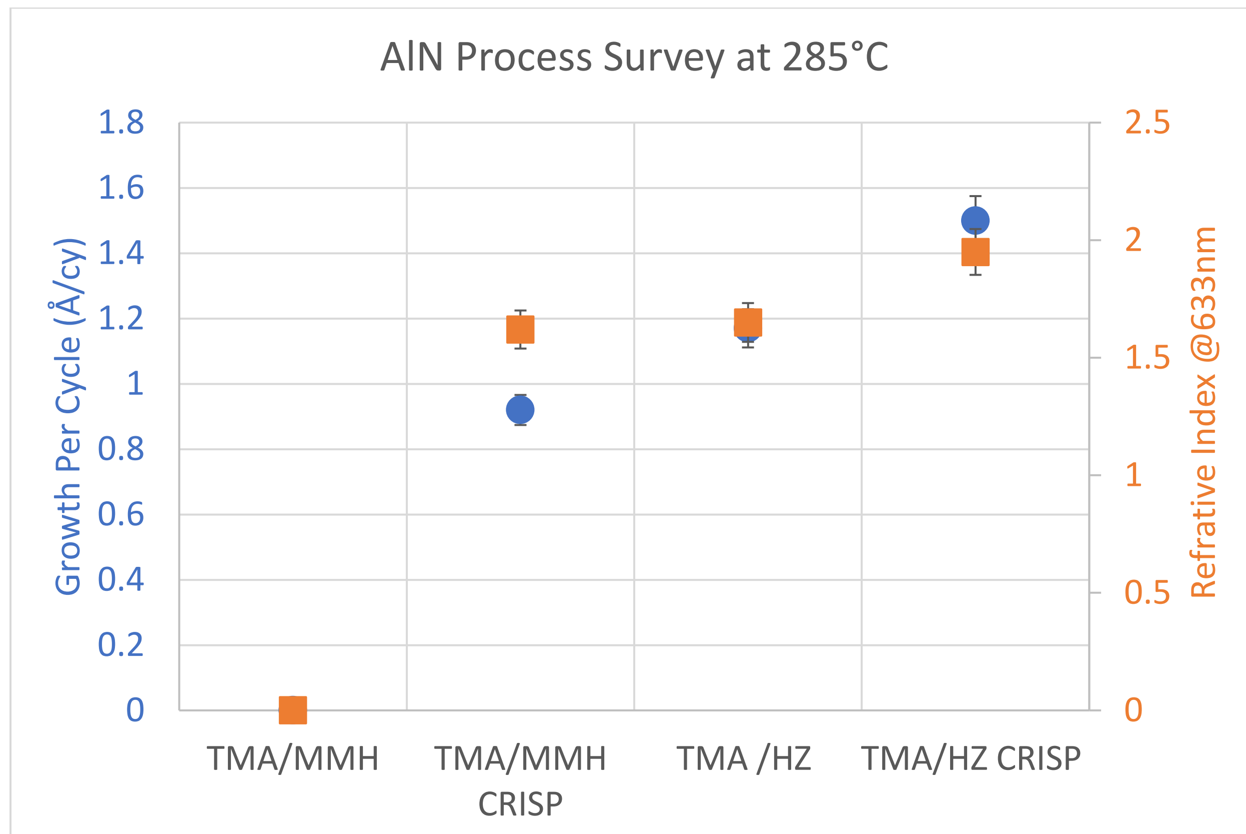
Novel Low Temperature Thermal ALD of Aluminum Nitride Utilizing a Non-Metal Catalyst

Figure 1: Refractive index (RI) and growth per cycle (GPC) for TMA/MMH and TMA/HZ processes with and without nonmetal catalyst incorporation (CRISP). Note that for the TMA/MMH process, no film was observed at 285 °C, so film properties are shown as a zero value.



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